



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

AF 13720/45

Applicant: David M. Curran, et al.

Docket No: TI-29038

Serial No: 10/029,788

Conf. No: 5683

Examiner: Timothy V. Eley

Art Unit: 3724

Filed: 10/26/2001

For: METHOD FOR REDUCING THE THICKNESS OF SPIN-ON GLASS ON SEMICONDUCTOR WAFERS

**NOTICE OF APPEAL FROM THE PRIMARY EXAMINER
TO THE BOARD OF APPEALS**

Mail Stop AF
Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on 3-29-04.

Ann Trent

Dear Sir:

Applicants hereby appeal to the Board of Appeals from the decision of the Primary Examiner mailed December 31, 2003, finally rejecting Claims 1-8 and 15-20.

The item(s) checked below are appropriate:

1. ☐ An extension of time to respond to the final rejection

☐ was granted on _____.
☐ is requested for ____ month.

2. ☒ A timely response to the final rejection has been

3. ☒ Fee \$330.00:

☐ Not required (Fee paid in prior appeal)

☒ The Commissioner of Patents is hereby authorized to charge any fees which may be required or credit any overpayment to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.
This form is submitted in triplicate.

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Texas Instruments Incorporated
P.O. Box 655474, MS 3999
Dallas, TX 75265
(972) 917-4371

W. James Brady III
Attorney for Appellants
Reg. No. 32,080